



## Product Change Notice

Micron PCN: 30840

Date: 3/1/2013

<b>Type of Change:</b>	Manufacturing Process Change	
<b>Title of Change:</b>	Automotive e•MMC Firmware and Manufacturing Changes	
<b>Description of Change:</b>	<p>Automotive e•MMC will be manufactured with the following changes:</p> <ul style="list-style-type: none"> <li>• Polyimide die coating (new passivation layer) on the NAND die (L73A/L74A) will improve manufacturability of multi-die packages.</li> <li>• New controller version, PS8200FF, will improve the circuit's margin at cold.</li> <li>• BGA 100 assembly site will change from SPIL to AMKOR Korea, including new substrate design with improved signal integrity.</li> <li>• New Firmware.</li> <li>• MTFC8GLUEA-AIT assembly site will change from STATS ChipPAC to Amkor Korea.</li> </ul>	
<b>Reason for Change:</b>	Optimization of Manufacturing Efficiency and Product Enhancement	
<b>Contact Information:</b>	<p><u>AMERICAS:</u> ARAVIND RAMAMOORTHY <a href="mailto:ARAMAMO@MICRON.COM">ARAMAMO@MICRON.COM</a></p> <p><u>ASIA-PACIFIC:</u> JINGWEN YANG <a href="mailto:JYANG@MICRON.COM">JYANG@MICRON.COM</a></p>	<p><u>EMEA :</u> ANTONIO IORIO <a href="mailto:ANTONIOIORIO@MICRON.COM">ANTONIOIORIO@MICRON.COM</a></p> <p><u>JAPAN:</u> DAIGO TOYAMA <a href="mailto:DTOYAMA@MICRON.COM">DTOYAMA@MICRON.COM</a></p>

**Product Affected:** Automotive e•MMC

<u>Affected Micron Part Numbers</u>	<u>Replacement Part Numbers</u>	<u>Package</u>
MTFC4GLUDM-AIT	MTFC4GLGDM-AIT Z	BGA153
MTFC8GLUDM-AIT	MTFC8GLGDM-AIT Z	BGA153
MTFC8GLUEA-AIT	MTFC8GLGDM-AIT Z	BGA153
MTFC16GJUEF-AIT	MTFC16GJGEF-AIT Z	BGA169
MTFC32GJUEF-AIT	MTFC32GJGEF-AIT Z	BGA169
N2M400FDA311A30E	MTFC4GLGDQ-AIT Z	BGA100
N2M400FDA311A30F	MTFC4GLGDQ-AIT Z	BGA100
N2M400GDA321A30E	MTFC8GLGDQ-AIT Z	BGA100
N2M400GDA321A30F	MTFC8GLGDQ-AIT Z	BGA100
N2M400JDA341A30E	MTFC32GJGDQ-AIT Z	BGA100
N2M400JDA341A30F	MTFC32GJGDQ-AIT Z	BGA100
N2M400FDA311A3BE	MTFC4GLGDQ-AIT Z	BGA100
N2M400FDA311A3BF	MTFC4GLGDQ-AIT Z	BGA100
N2M400GDA321A3BE	MTFC8GLGDQ-AIT Z	BGA100
N2M400GDA321A3BF	MTFC8GLGDQ-AIT Z	BGA100
N2M400HDA321A3BE	MTFC16GJGDQ-AIT Z	BGA100
N2M400HDA321A3BF	MTFC16GJGDQ-AIT Z	BGA100
N2M400JDA341A3BE	MTFC32GJGDQ-AIT Z	BGA100
N2M400JDA341A3BF	MTFC32GJGDQ-AIT Z	BGA100
N2M400KDA345K3BE	MTFC64GJGDN-AIT Z	BGA169
N2M400KDA345K3BF	MTFC64GJGDN-AIT Z	BGA169

Note: Per JEDEC Standard JESD46-C Section 3.2.3; lack of acknowledgment of this PCN within 30 days constitutes acceptance of change



---

**Method of Identification:**

- Part Numbers change (see table above)
- New PRV field in CID register change from "3.x" to "4.x" will identify new controller version.

---

**Micron Sites Affected:** Fabrication — FAB2 (Lehi, UT, US), FAB6 (Manassas, VA, US)  
Assembly — Subcontractor

---

**Product/Data Availability**

**New Production:**

*Sample Availability:* April 2013

*Qual Data Availability:* June 2013

*Production Shipments:* July 2013

**Old Production:**

*Last Time Buy:* Dec 2013

*Last Time Ship* June 2014

---

**Qualification Plan:** Product manufactured with the changes described above will be qualified according to Company qualification procedure and best practices. Qualification plan will be available upon request.

---

Orders placed prior to the LTB date are subject to current inventory levels, which may vary based on market conditions and customer demand. Early orders are encouraged.